

T-P-6 Series – Void Filler (0.50 - 5.00mm Shore 00 45/65)

DATASHEET



T-P-6 Series (0.50 - 5.00mm
Shore 00 45/65)

FEATURES

- Soft with High Compressibility
- 3.0 W/mK Thermal Conductivity
- Low Thermal Impedance
- UL94 V0 Recognised
- Naturally Tacky

APPLICATIONS

- Electronic Components: IC, CPU, MOS, LED, M/B, P/S, Heat Sinks, LCD-TV's, Notebook PC, PC, Telecommunication Devices
- Wireless Hubs, DDR Modules, DVD Applications, Hand-set Applications etc.

PROPERTIES	TEST METHOD	UNIT	T-P-6 SERIES
Material	-	-	Ceramic Powder filled with Silicon Resin
Colour	Visual	-	Blue
Thickness (±10%)	ASTM-D374	mm	0.50 – 5.00
Increments of 0.25mm/0.01inch		inch	0.02 – 0.20
Hardness (±10)	ASTM-D2240	Shore 00	45 (≥1.0mm) 65 (<1.0mm)
Thermal Conductivity	ASTM-D5470	W/mK	3.0
Flammability Rating	UL94 V0 IEC 60695-11-10	-	UL94-V0
Dielectric Breakdown Voltage (1mm)	ASTM-D149	kV	≥10
Permittivity (1MHz)	ASTM-D150	-	6.33
Specific Gravity (±0.2)	ASTM-D792	g/cm ³	2.89
Working Temperature	EM344	°C	-40 to 200
Volume Resistance	ASTM-D257	Ohm-cm	10 ¹²
Tensile Strength	ASTM-D412-1998A	MPa	0.23

Note:

1. Customised shapes are available;
2. The above performance data is tested in an environment of 70% humidity, temperature 25°C.
3. This data is intended for reference purposes only. It is recommended that the material is tested to fully evaluate its performance ensuring it is fit for purpose.

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